

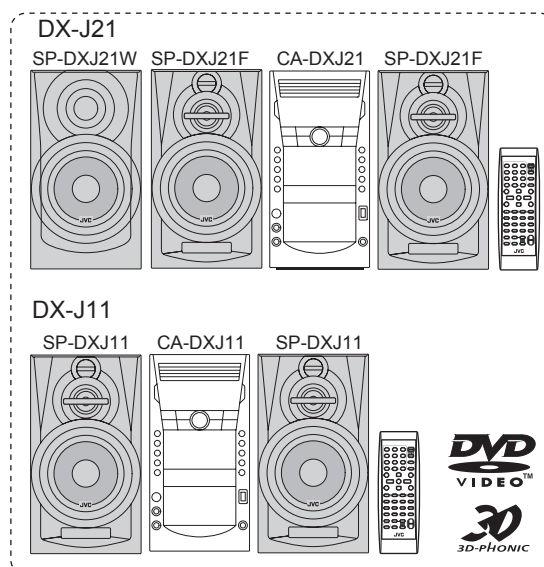
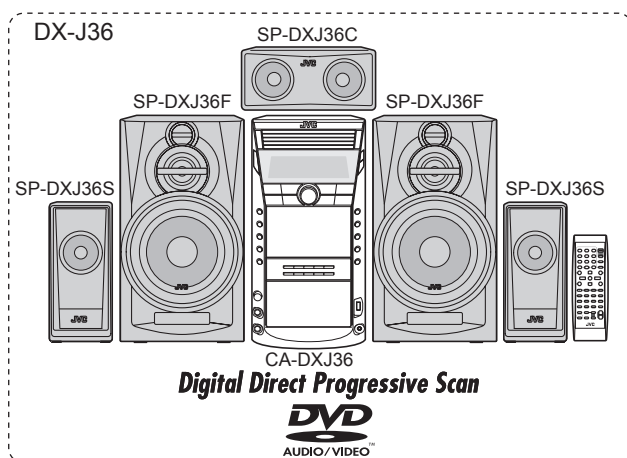
JVC

SCHEMATIC DIAGRAMS

COMPACT COMPONENT SYSTEM

DX-J36UN,DX-J36EE,DX-J36UX,DX-J36UG
DX-J21UN,DX-J21J,DX-J21EE,DX-J21A
DX-J21UW,DX-J21UX,DX-J21UG
DX-J11UN,DX-J11EE,DX-J11UW
DX-J11UX,DX-J11UG,DX-J11UH

DVD-ROM No.SML2008Q1



Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

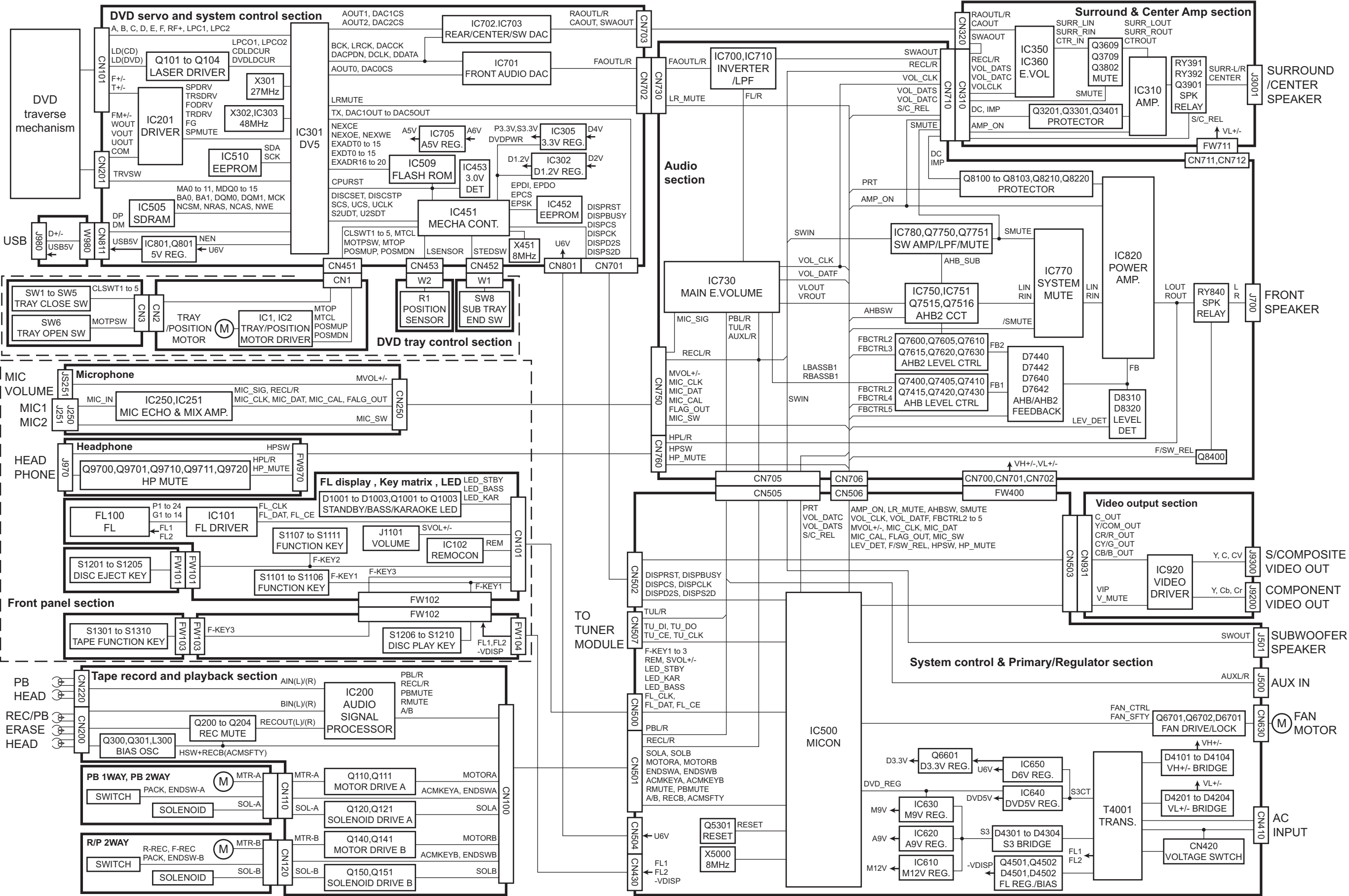
Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)

Contents

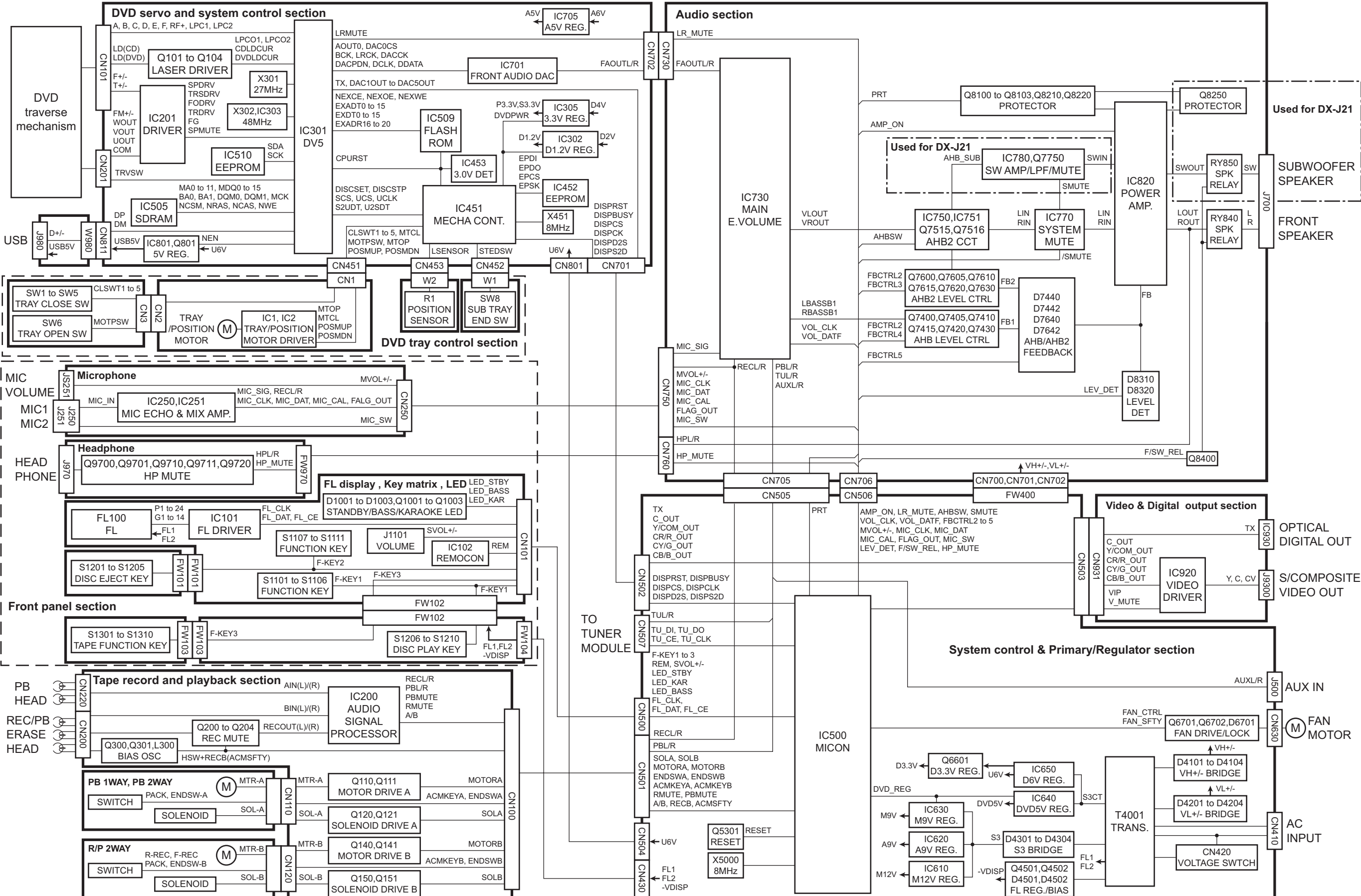
Block diagrams	2-1
Standard schematic diagrams	2-2
Printed circuit boards	2-20 to 22

In regard with component parts appearing on the silk-screen printed side (parts side) of the PWB diagrams, the parts that are printed over with black such as the resistor (■), diode (▬) and ICP (●) or identified by the "A" mark nearby are critical for safety.

Block diagram (For DX-J36)

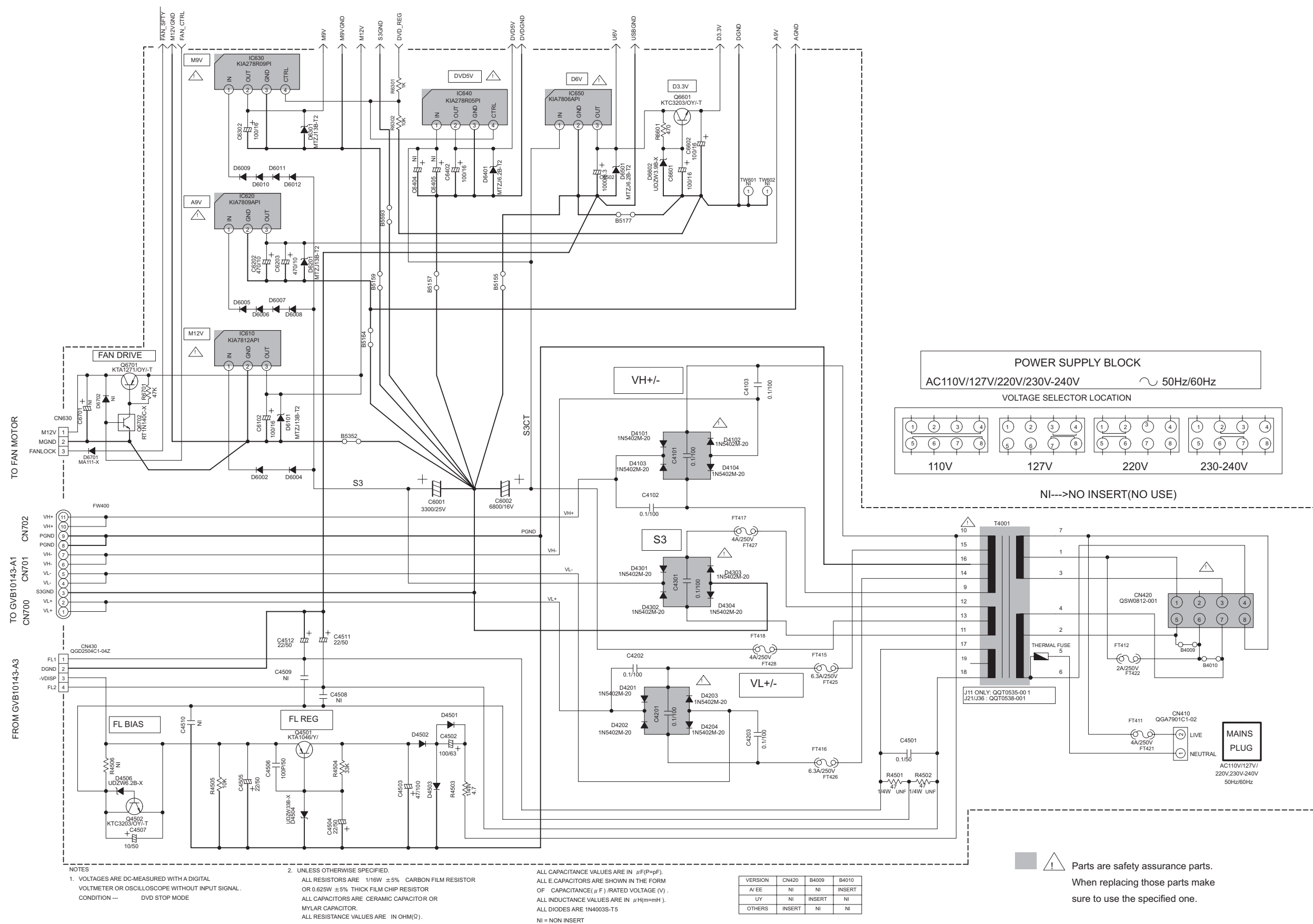


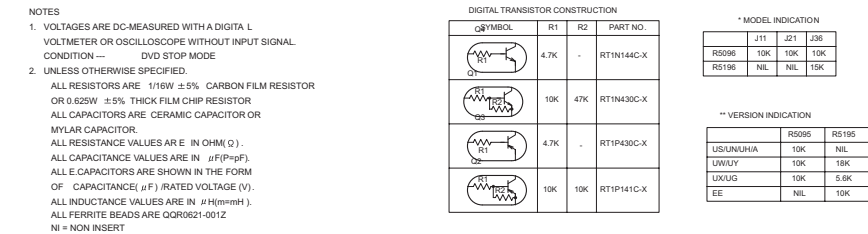
Block diagram (For DX-J11 and DX-J21)



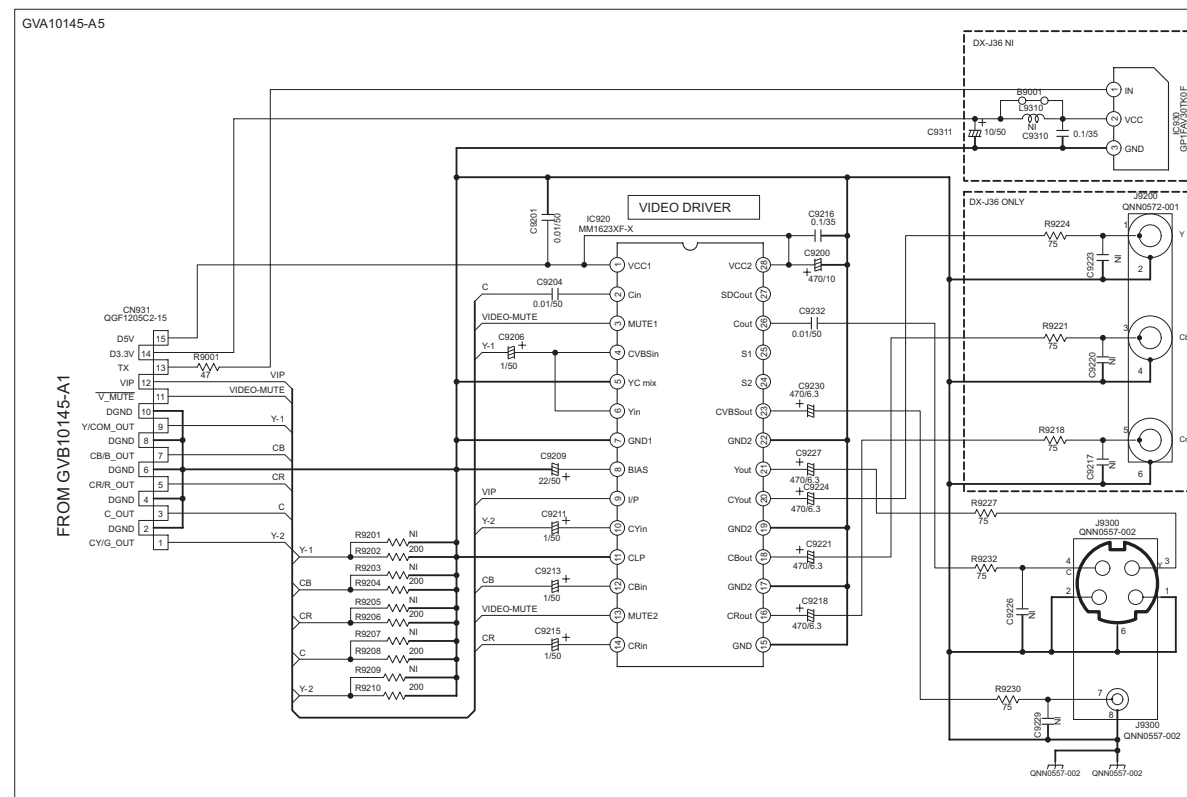
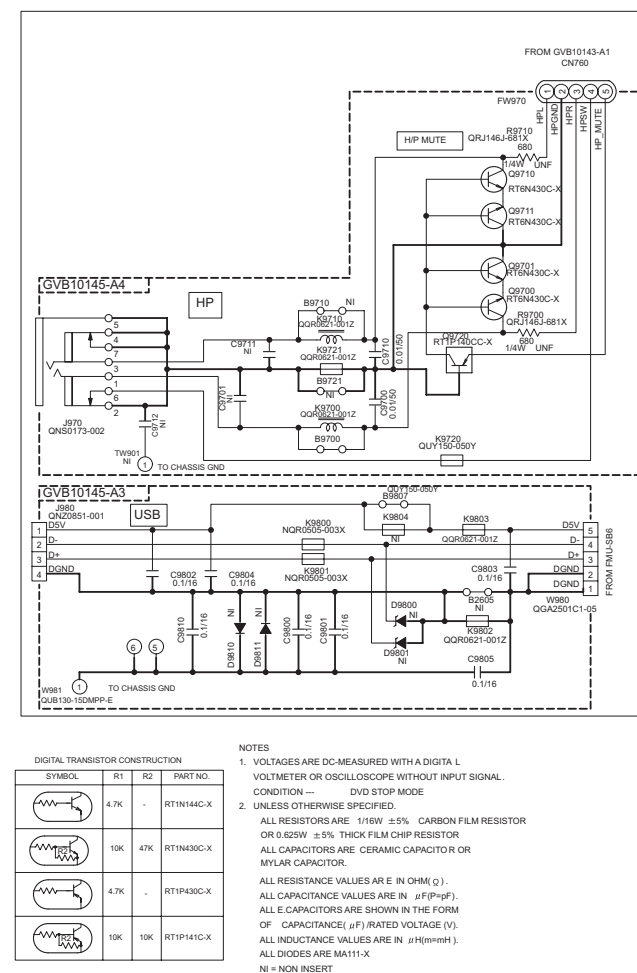
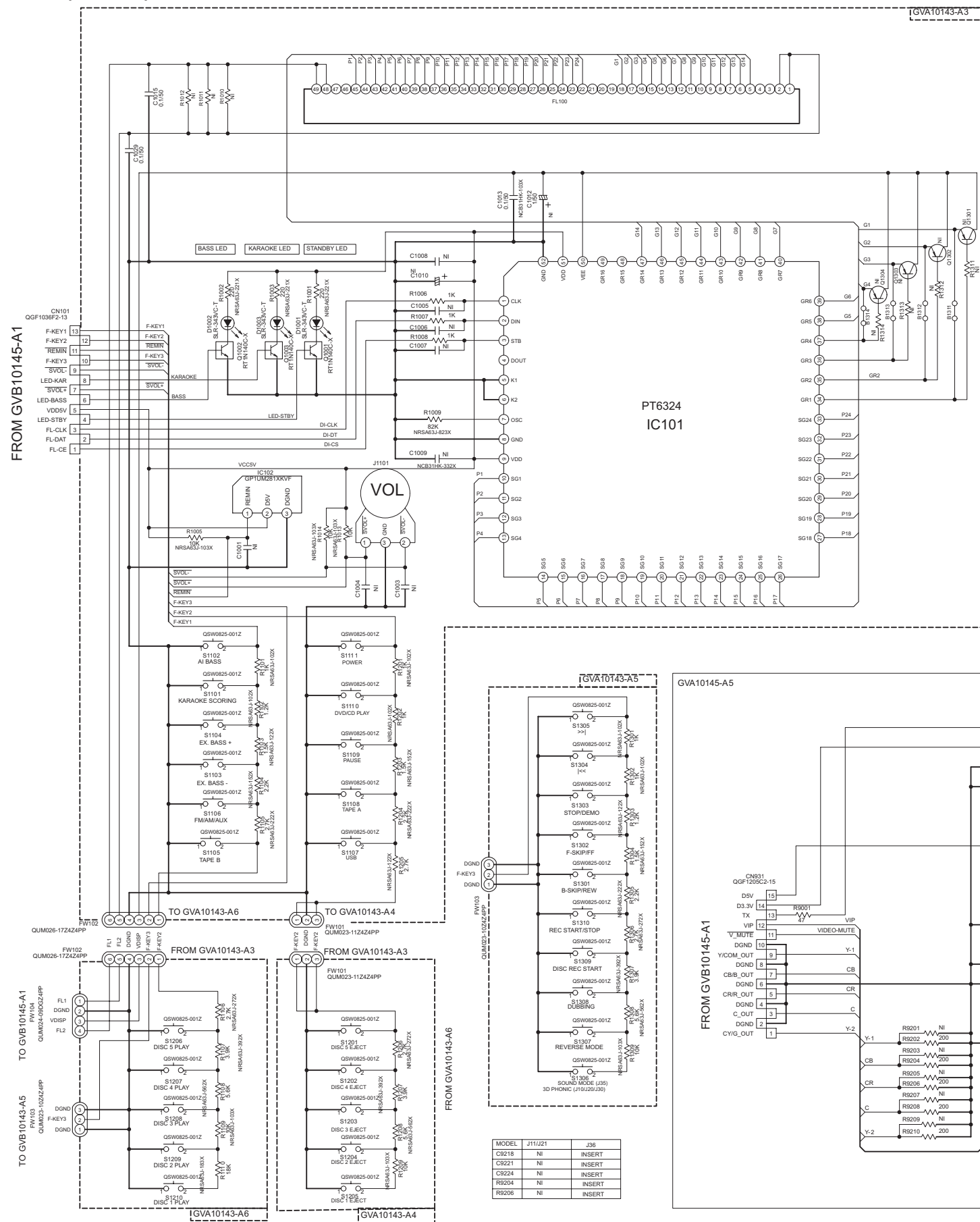
Standard schematic diagrams

■ Primary section (DX-J36)

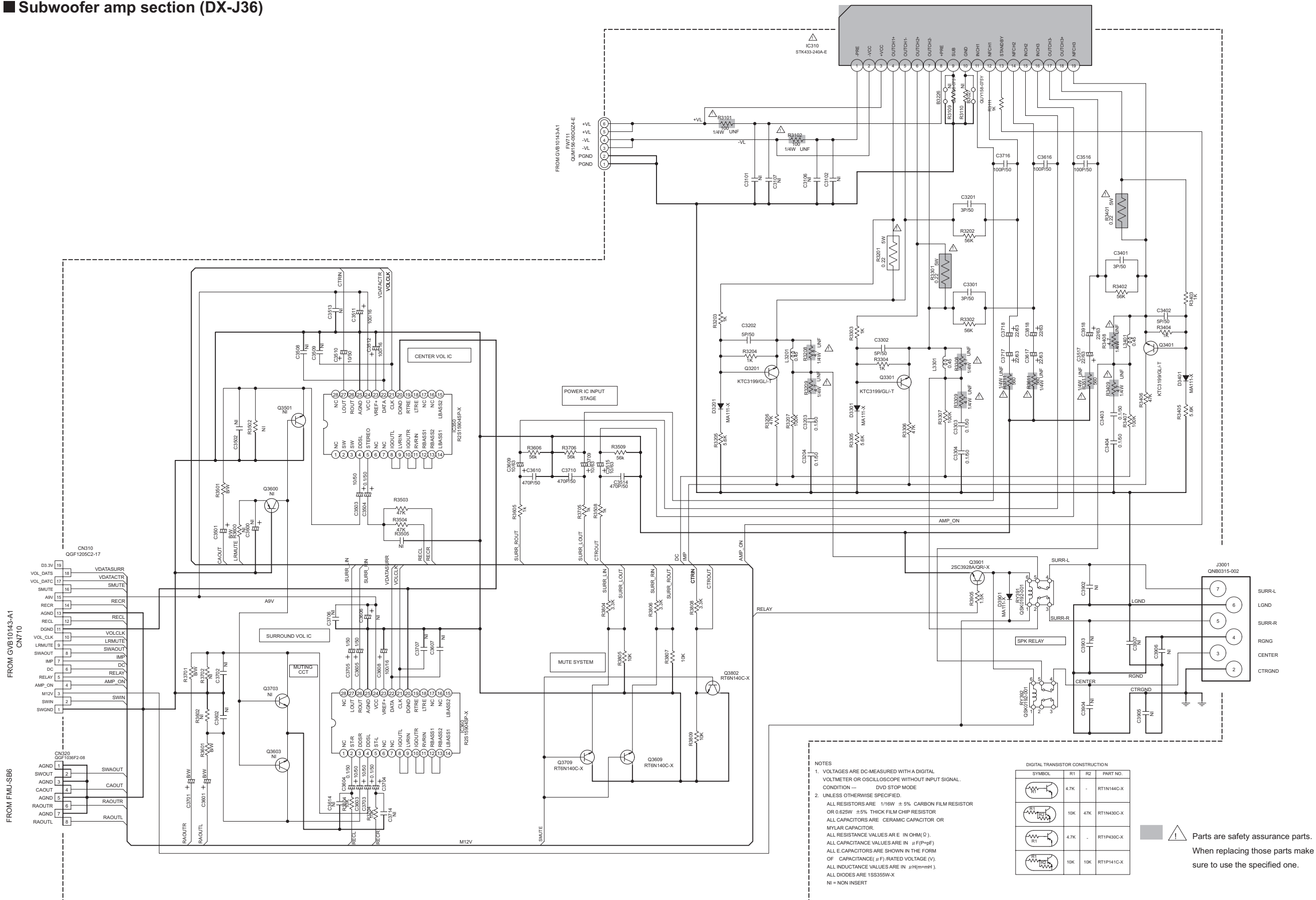


[illegible]

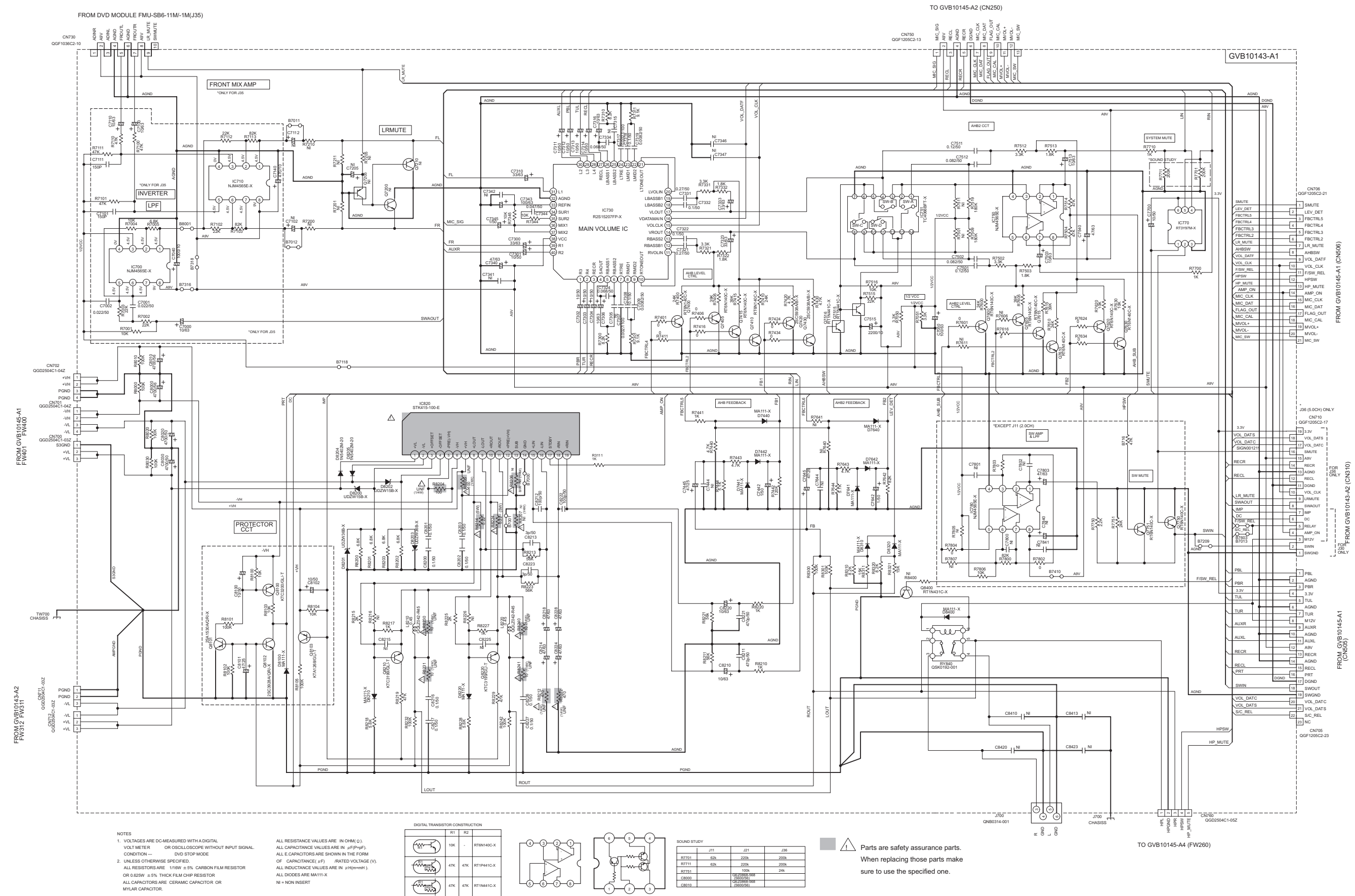
■ Front section (DX-J36)



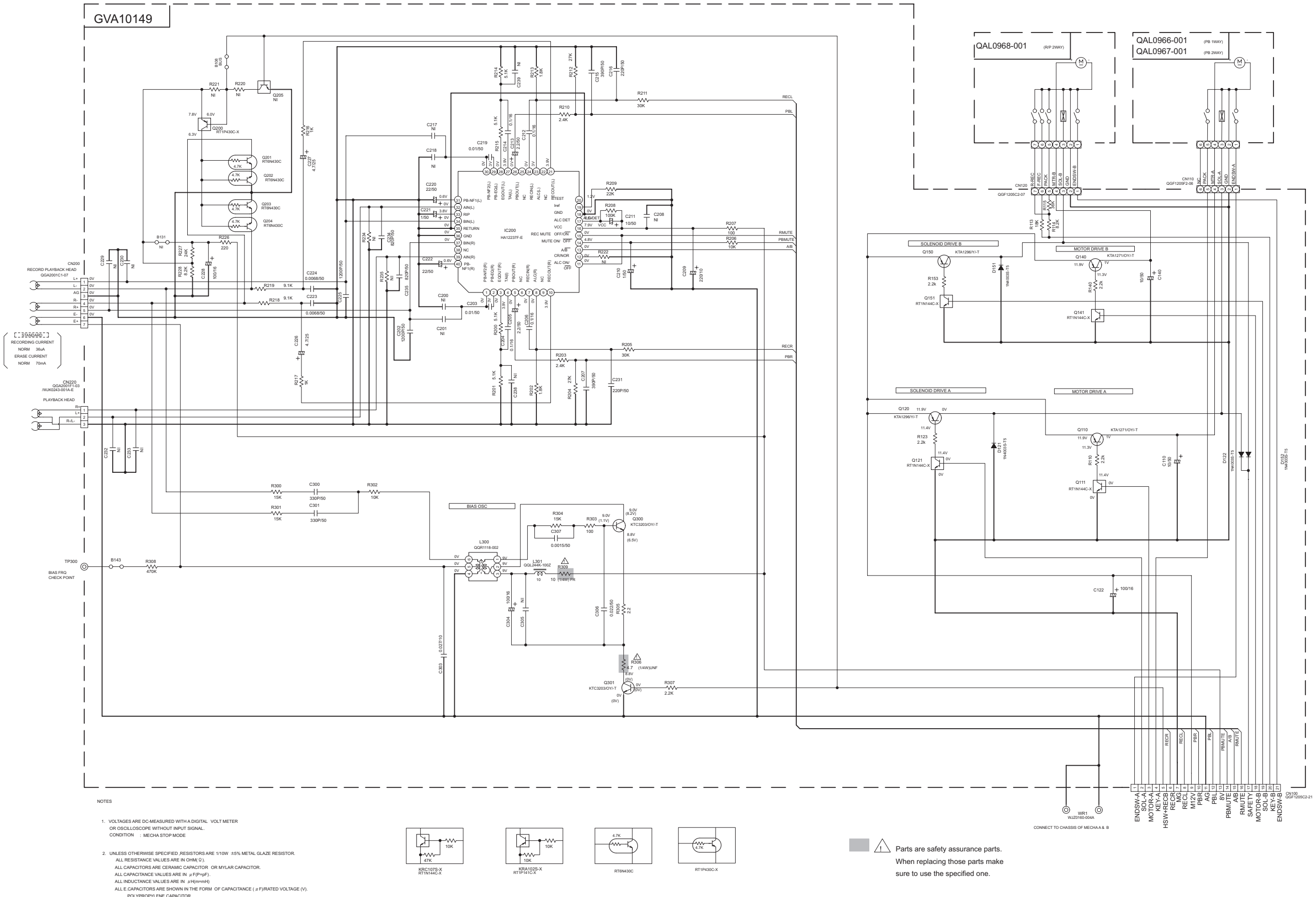
■ Subwoofer amp section (DX-J36)



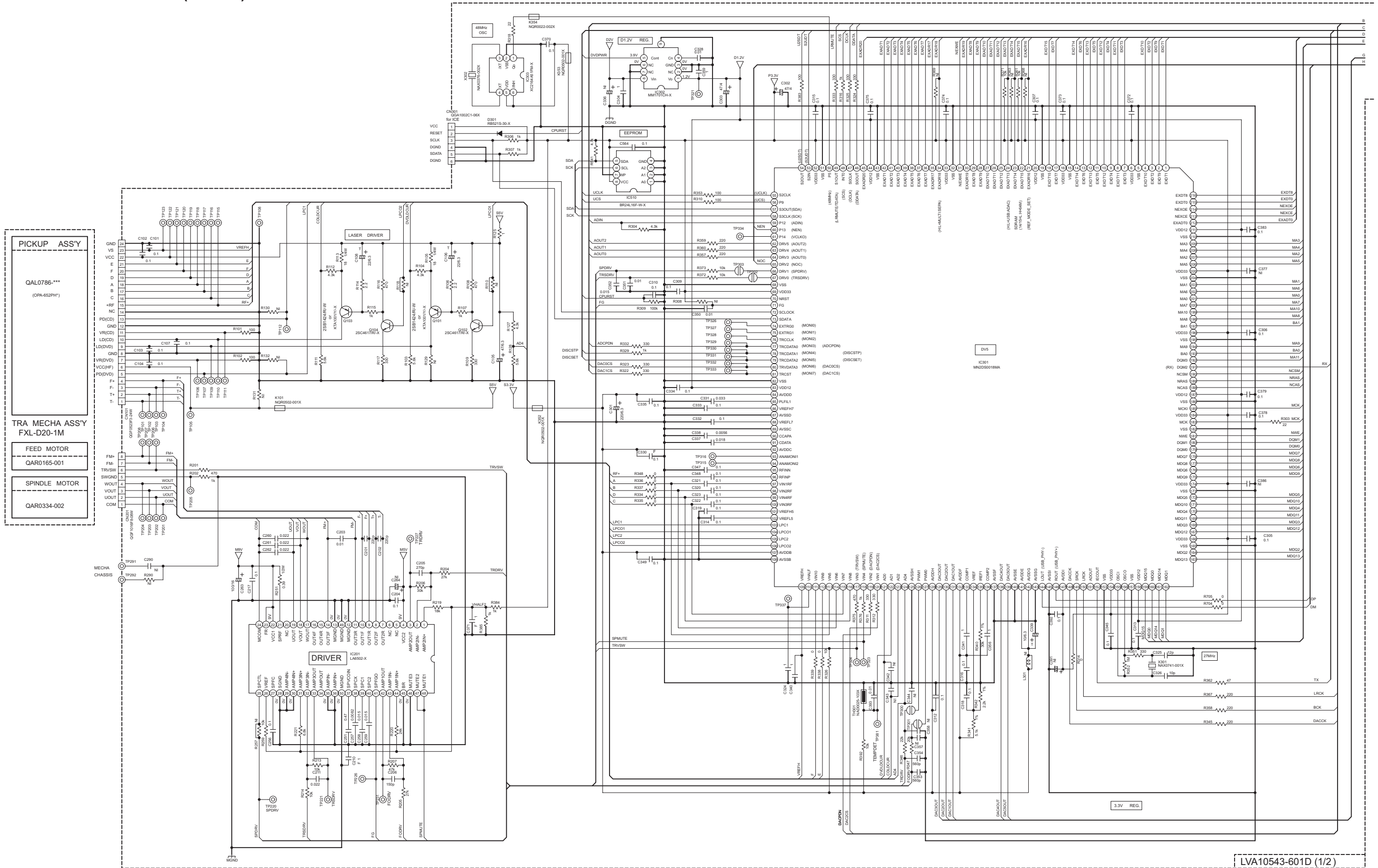
■ Audio section (DX-J36)



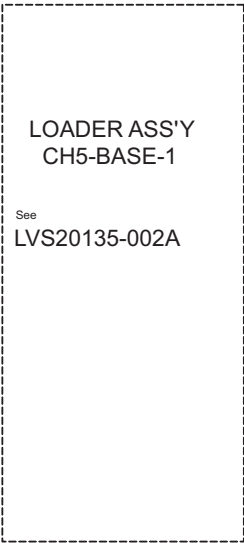
■ Cassette control section (DX-J36)



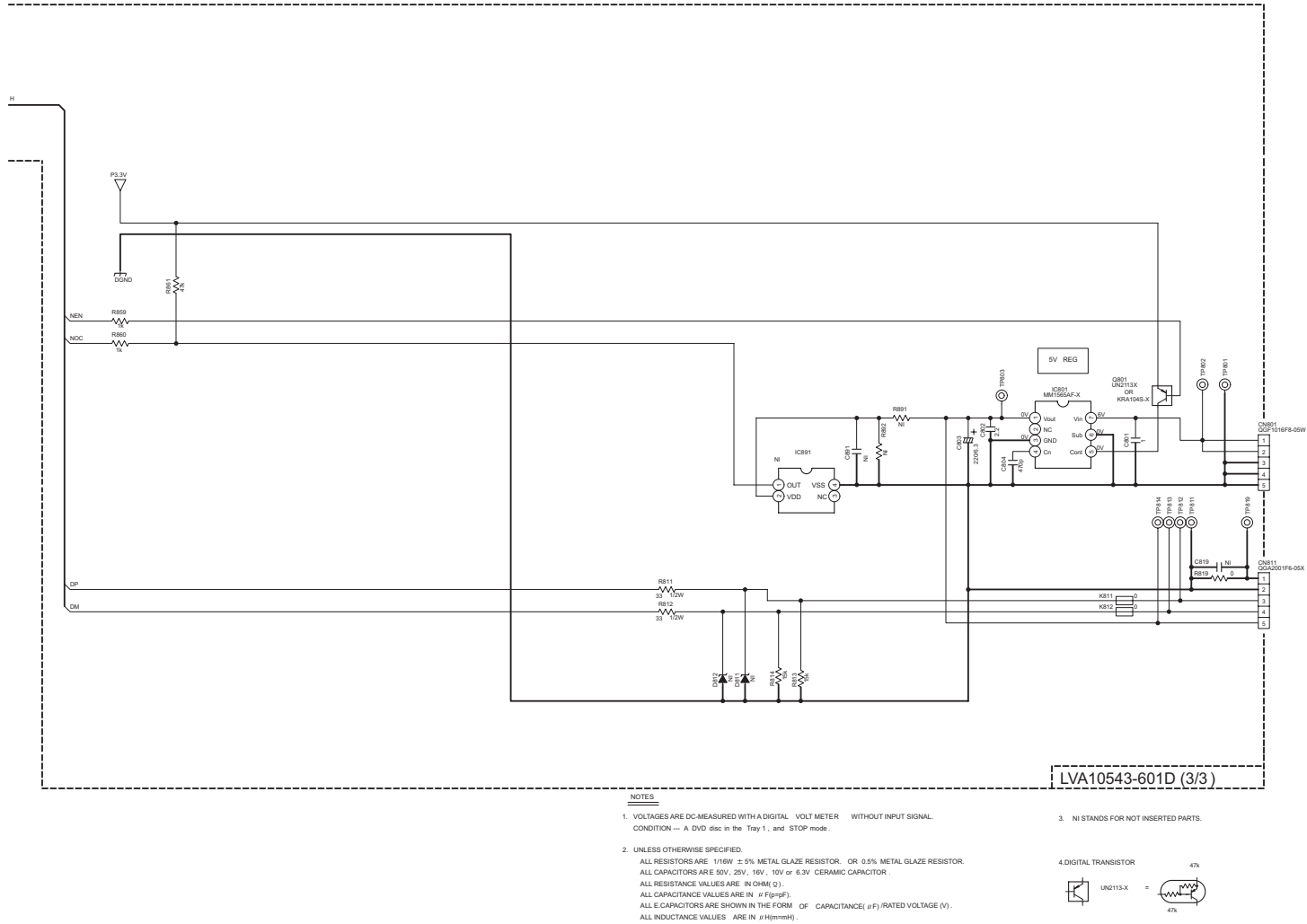
■ Front end section 1 (DX-J36)



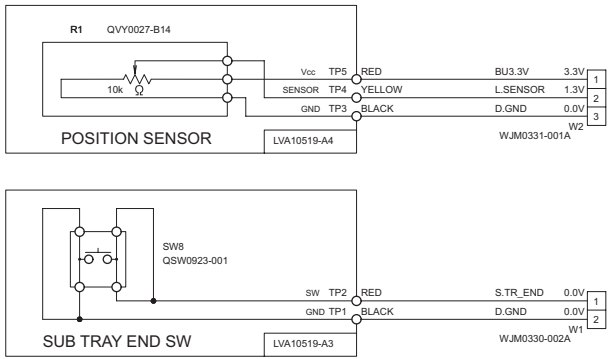
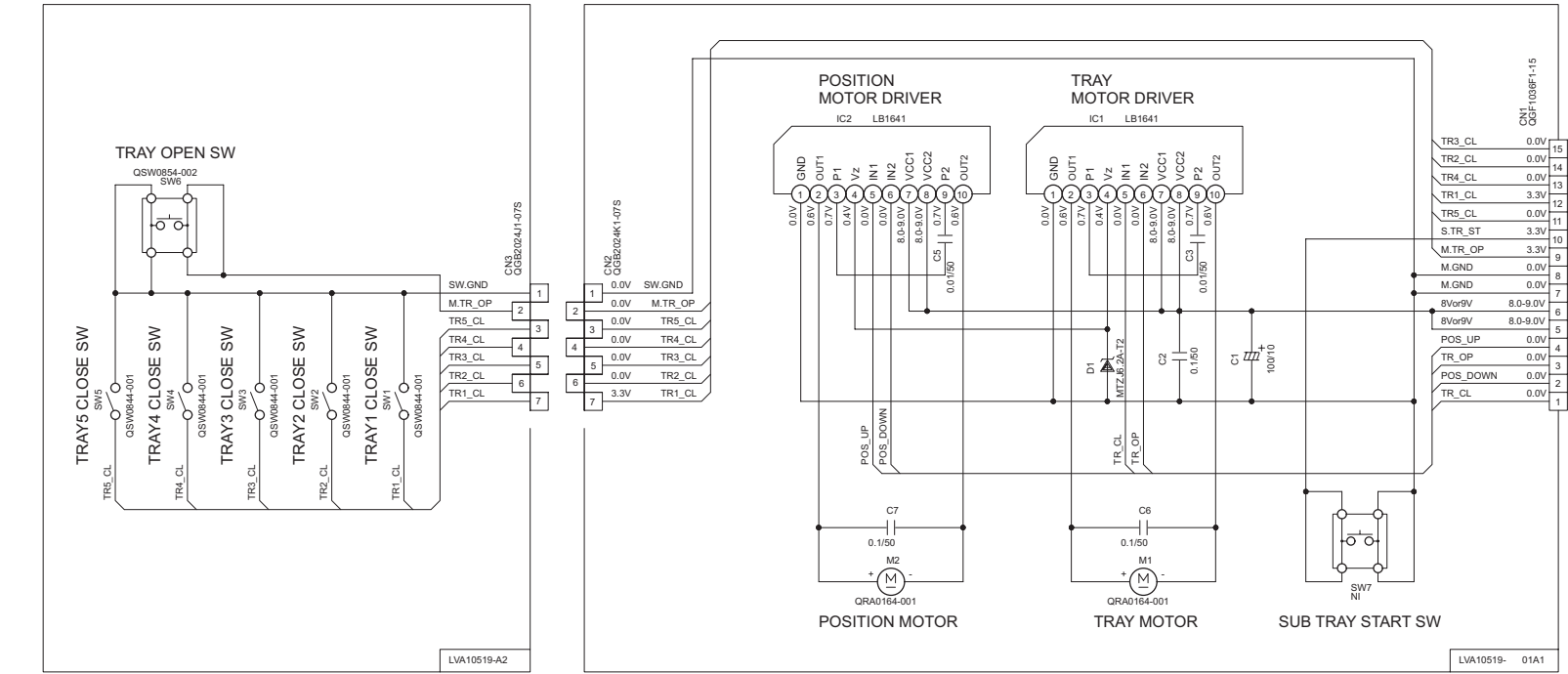
■ Front end section 2 (DX-J36)



■ Front end section 3 (DX-J36)

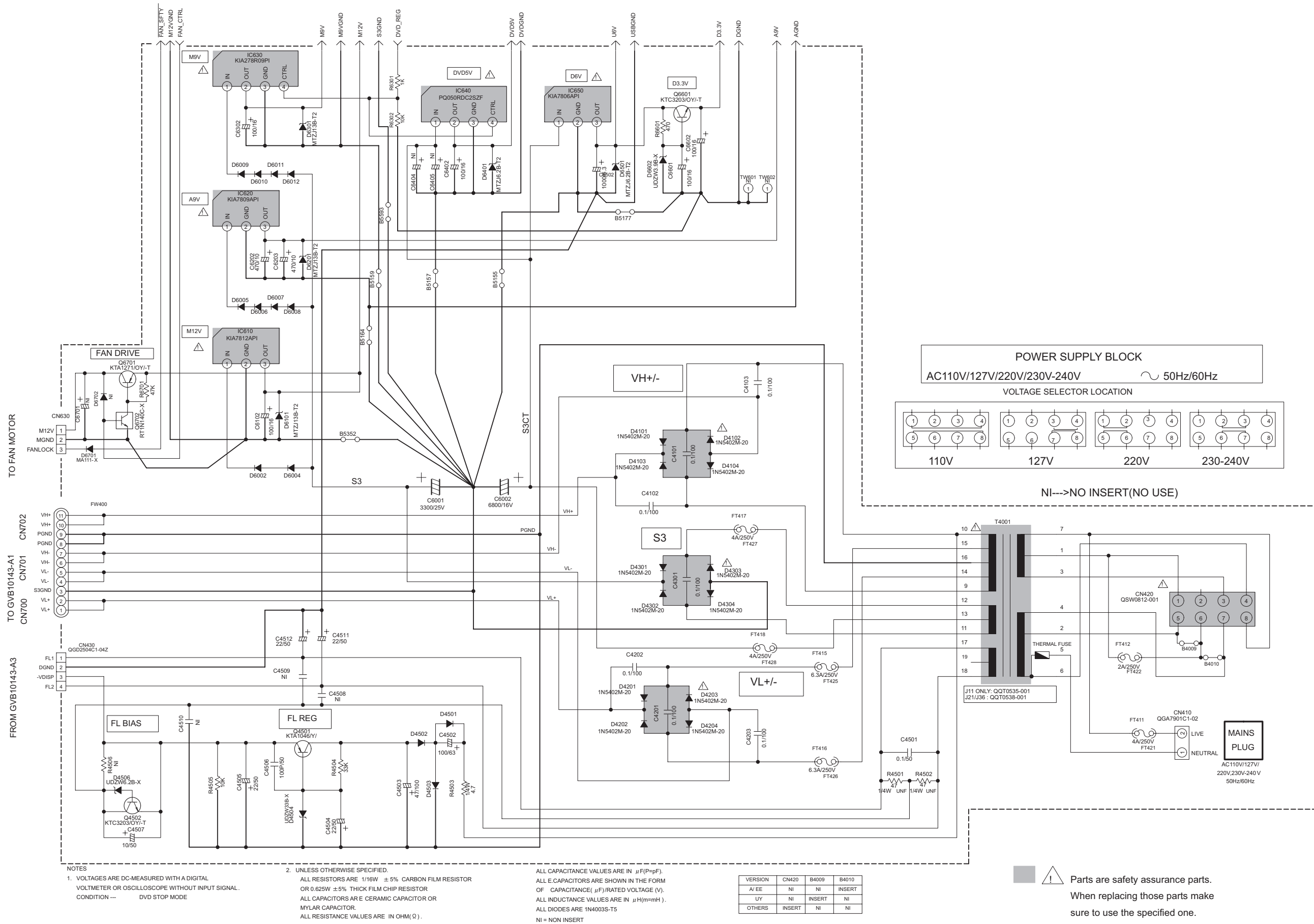


■ Loader section (DX-J36)

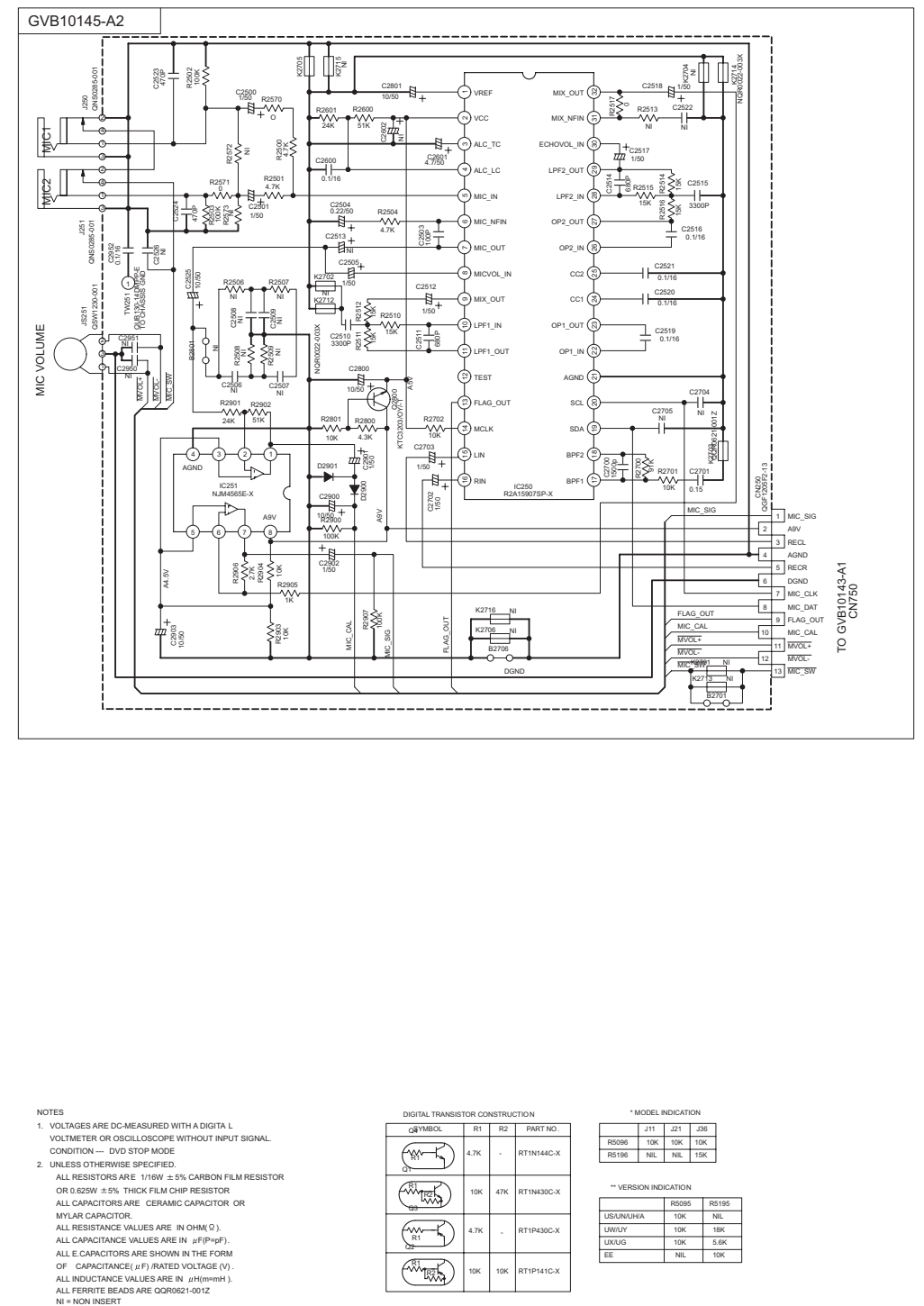
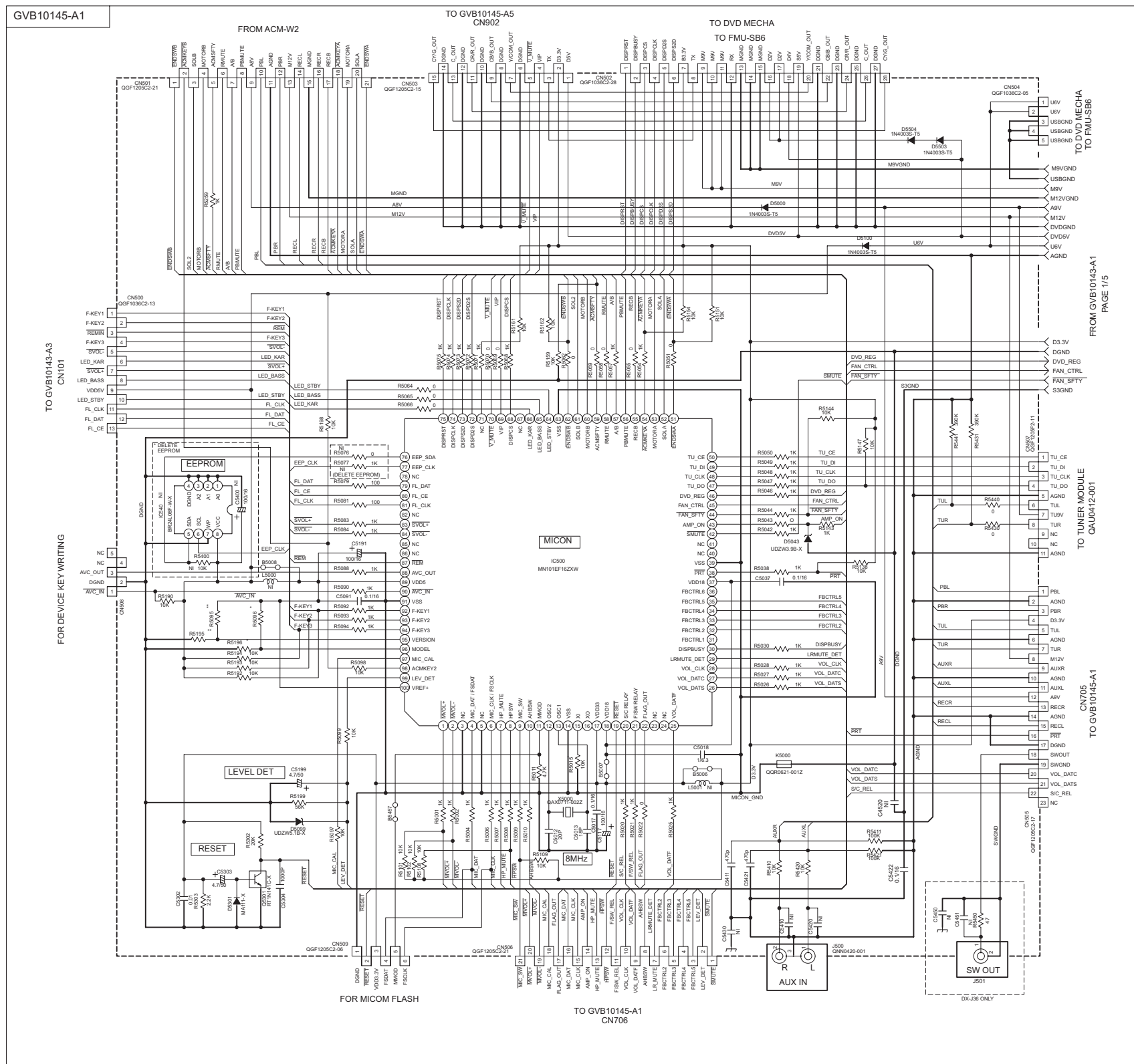


- NOTES
- VOLTAGES ARE DC-MEASURED WITH A DIGITAL VOLT METER.
CONDITION: DISC1 STOP
 - UNLESS OTHERWISE SPECIFIED:
ALL CAPACITORS ARE SHOWN IN THE FORM OF CAPACITANCE (μF) / RATED VOLTAGE (V).
 - NI STANDS FOR NOT INSERTED PARTS.

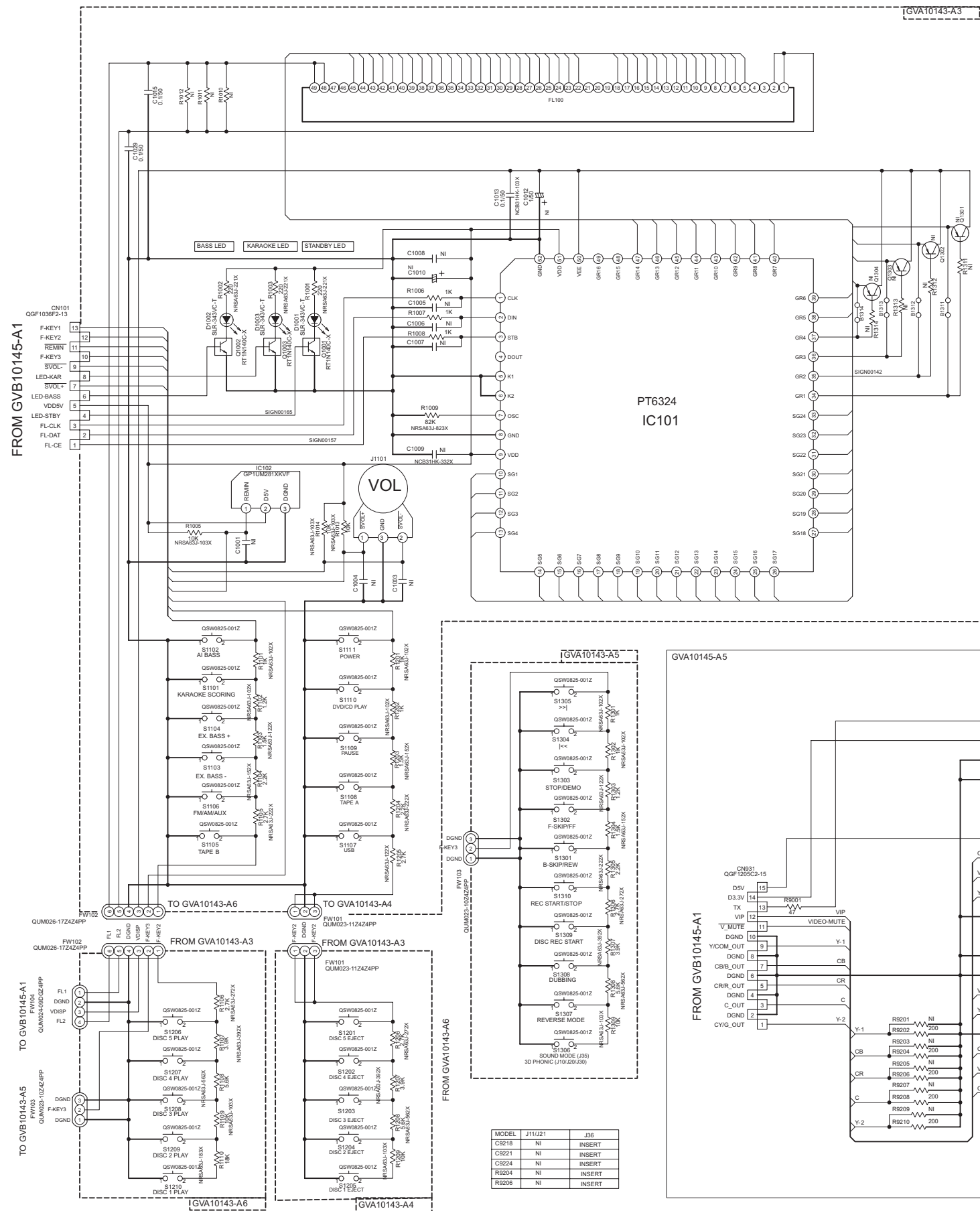
■ Primary section (DX-J21,DX-J11)



■ Micom section (DX-J21,DX-J11)



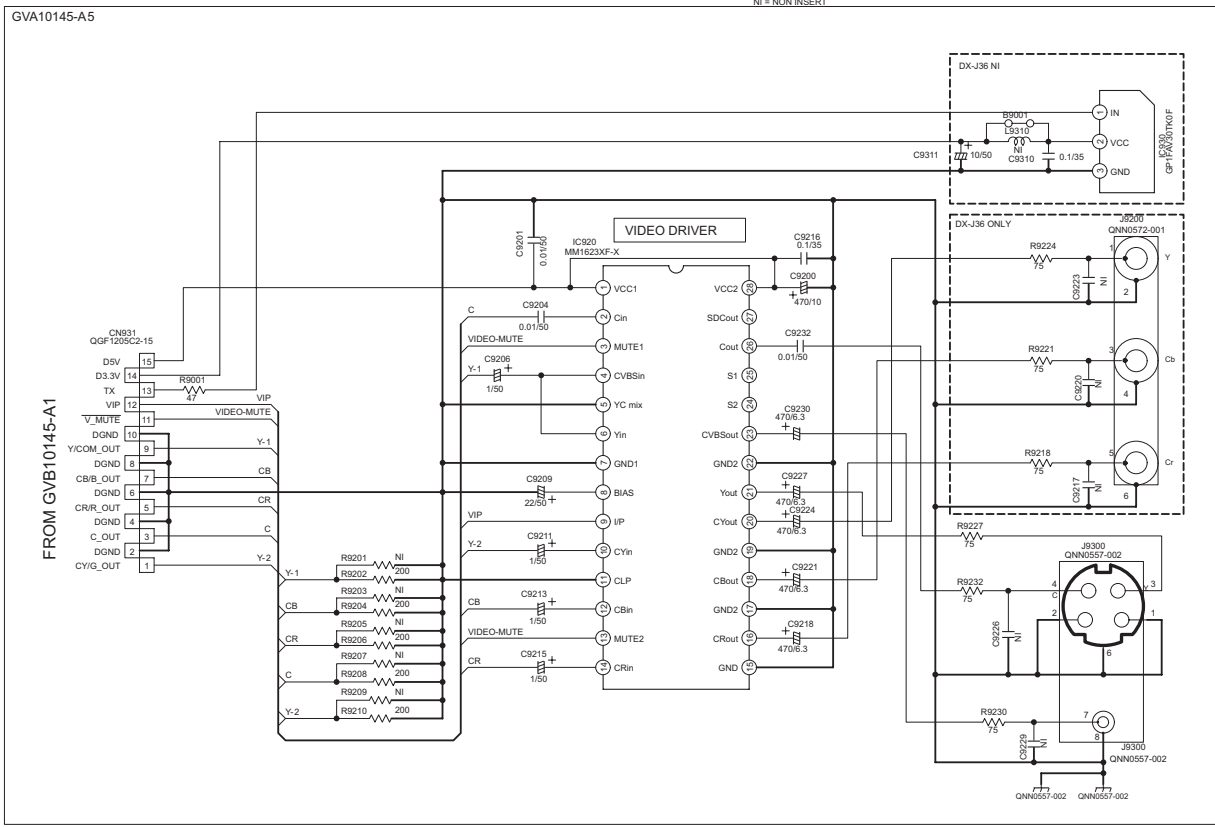
■ Front section (DX-J21,DX-J11)



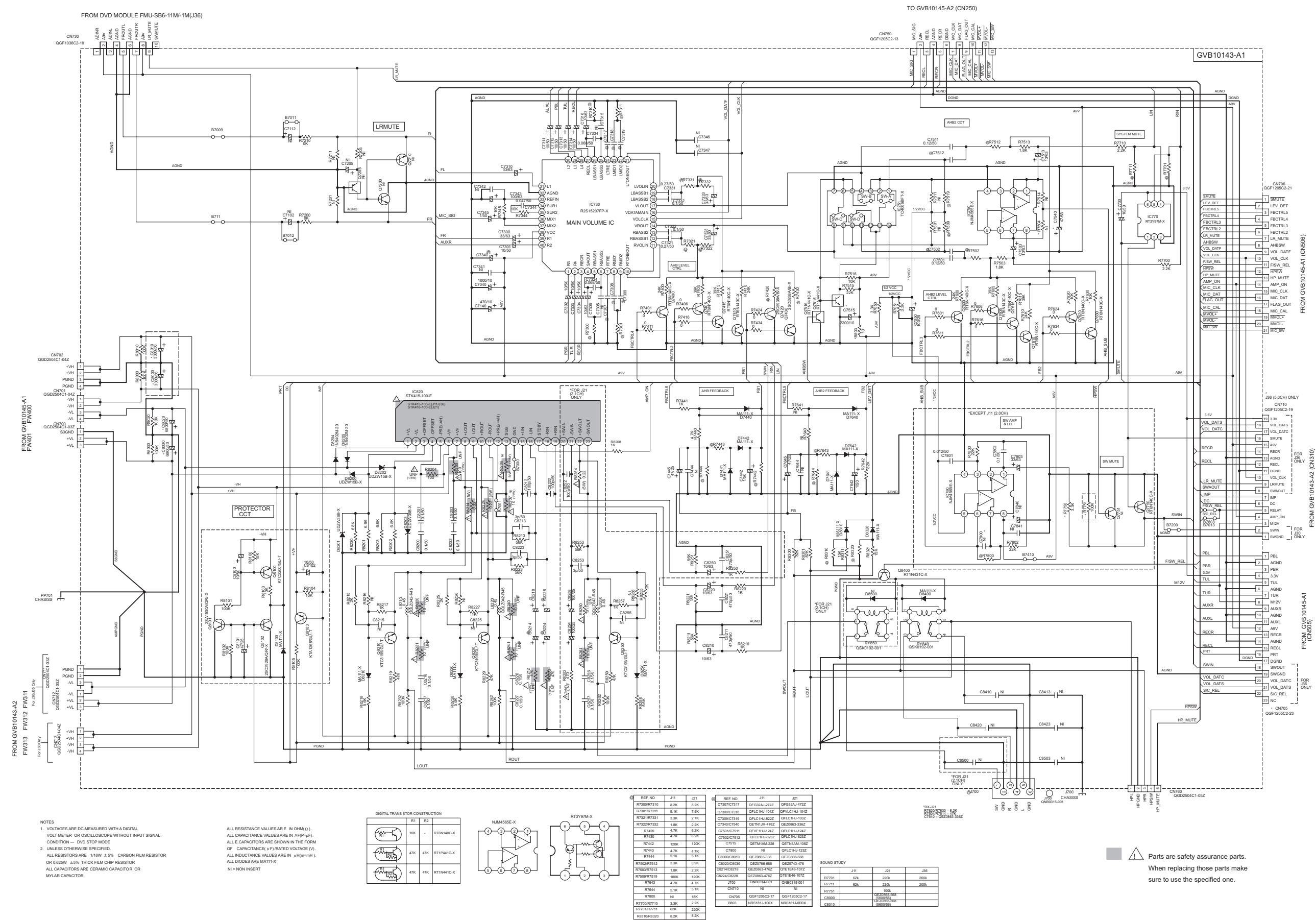
DIGITAL TRANSISTOR CONSTRUCTION

SYMBOL	R1	R2	PART NO.
	4.7K	-	RT1N144C-X
	10K	47K	RT1N430C-X
	4.7K	-	RT1P430C-X
	10K	10K	RT1P141C-X

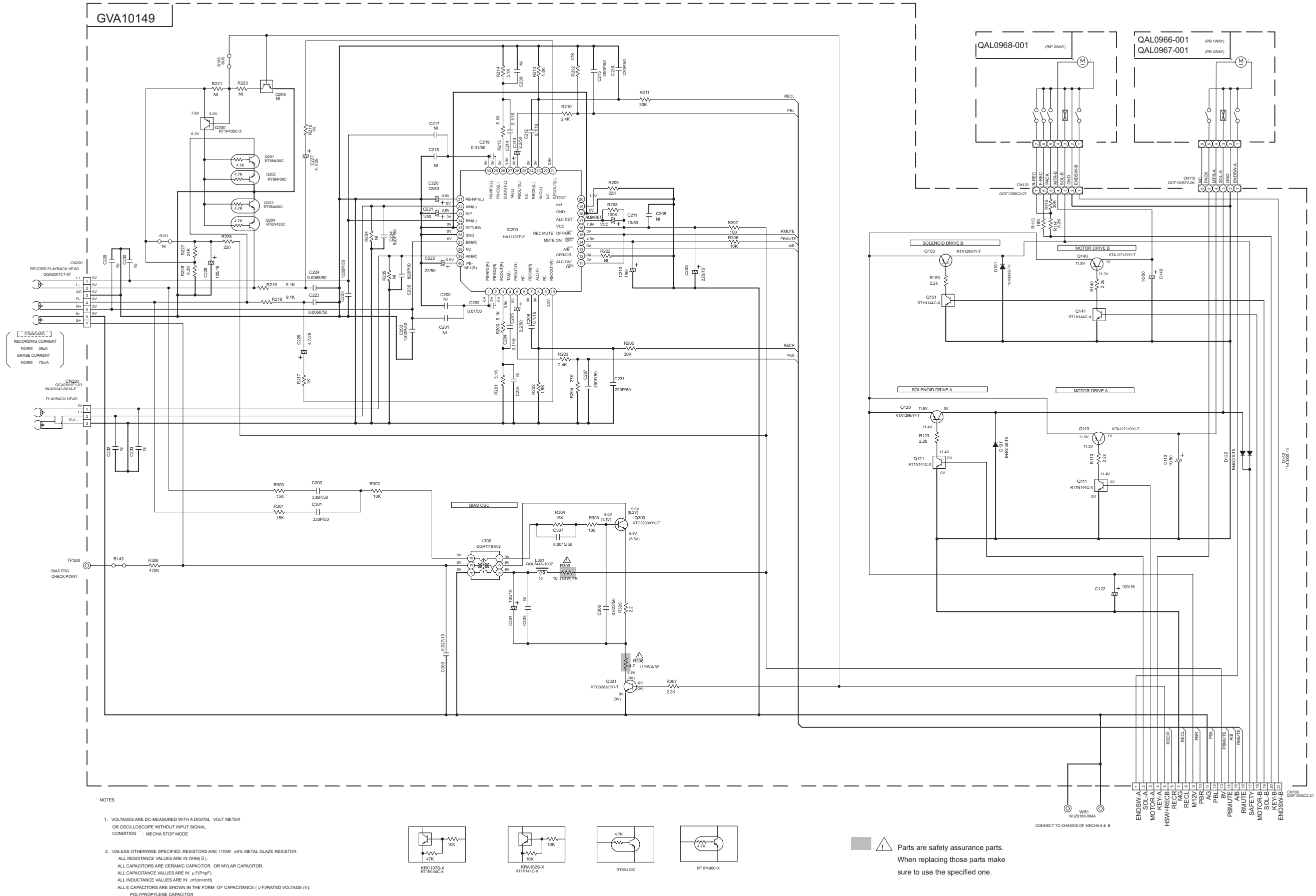
- NOTES
- VOLTAGES ARE DC-MEASURED WITH A DIGITAL VOLTMETER OR OSCILLOSCOPE WITHOUT INPUT SIGNAL. CONDITION - DVD STOP MODE
 - UNLESS OTHERWISE SPECIFIED:
ALL RESISTORS ARE: 1/16W ± 5% CARBON FILM RESISTOR OR 0.625W ± 5% THICK FILM CHIP RESISTOR
ALL CAPACITORS ARE: CERAMIC CAPACITOR OR MYLAR CAPACITOR.
ALL RESISTANCE VALUES ARE IN OHM (Ω).
ALL CAPACITANCE VALUES ARE IN nF (nF) or pF (pF).
ALL CAPACITORS ARE SHOWN IN THE FORM OF CAPACITANCE (μF) / RATED VOLTAGE (V).
ALL INDUCTANCE VALUES ARE IN μH (mH).
ALL DIODES ARE MAT111-X
NI = NON INSERT



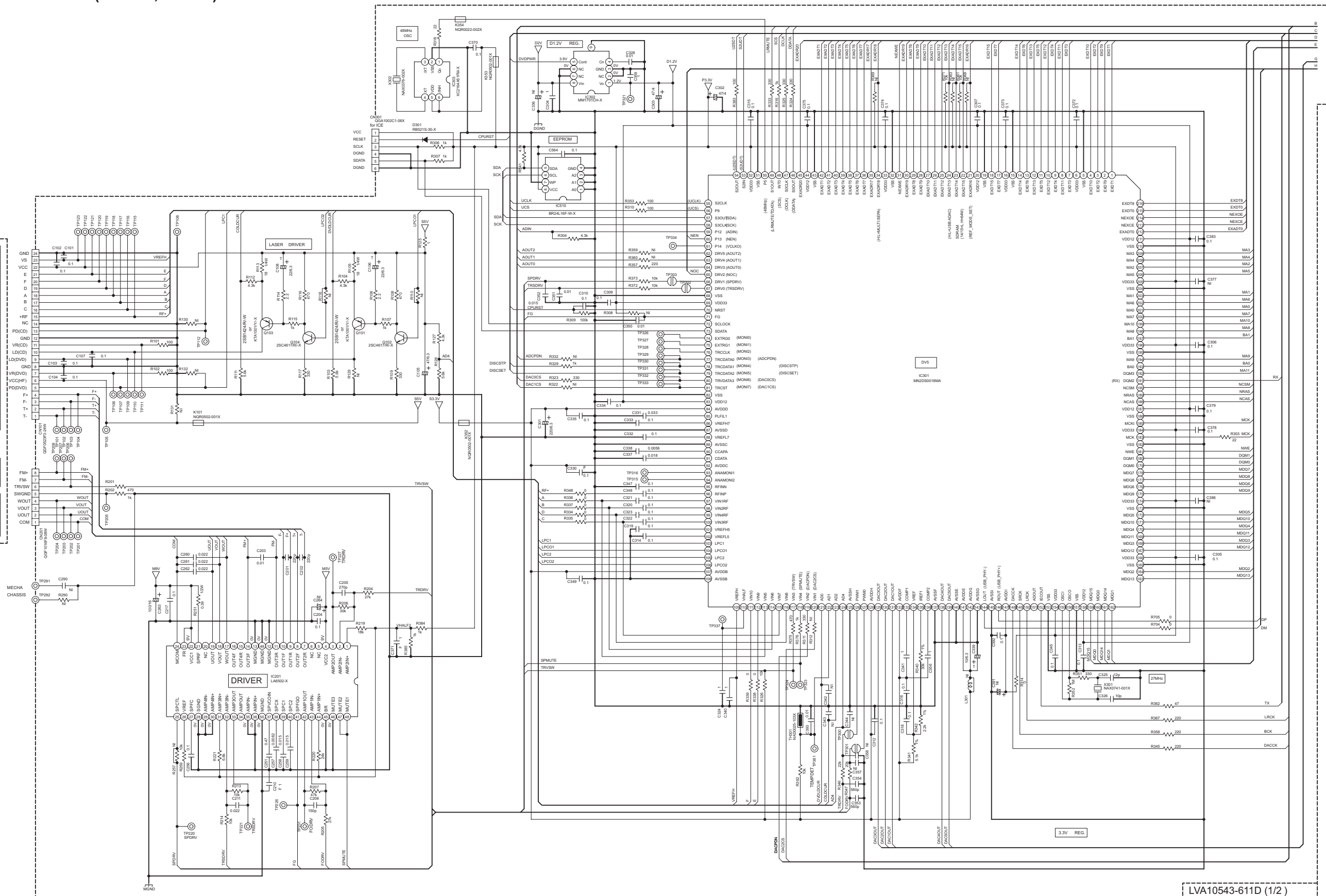
■ Audio section (DX-J21,DX-J11)



■ Cassette control section (DX-J21,DX-J11)



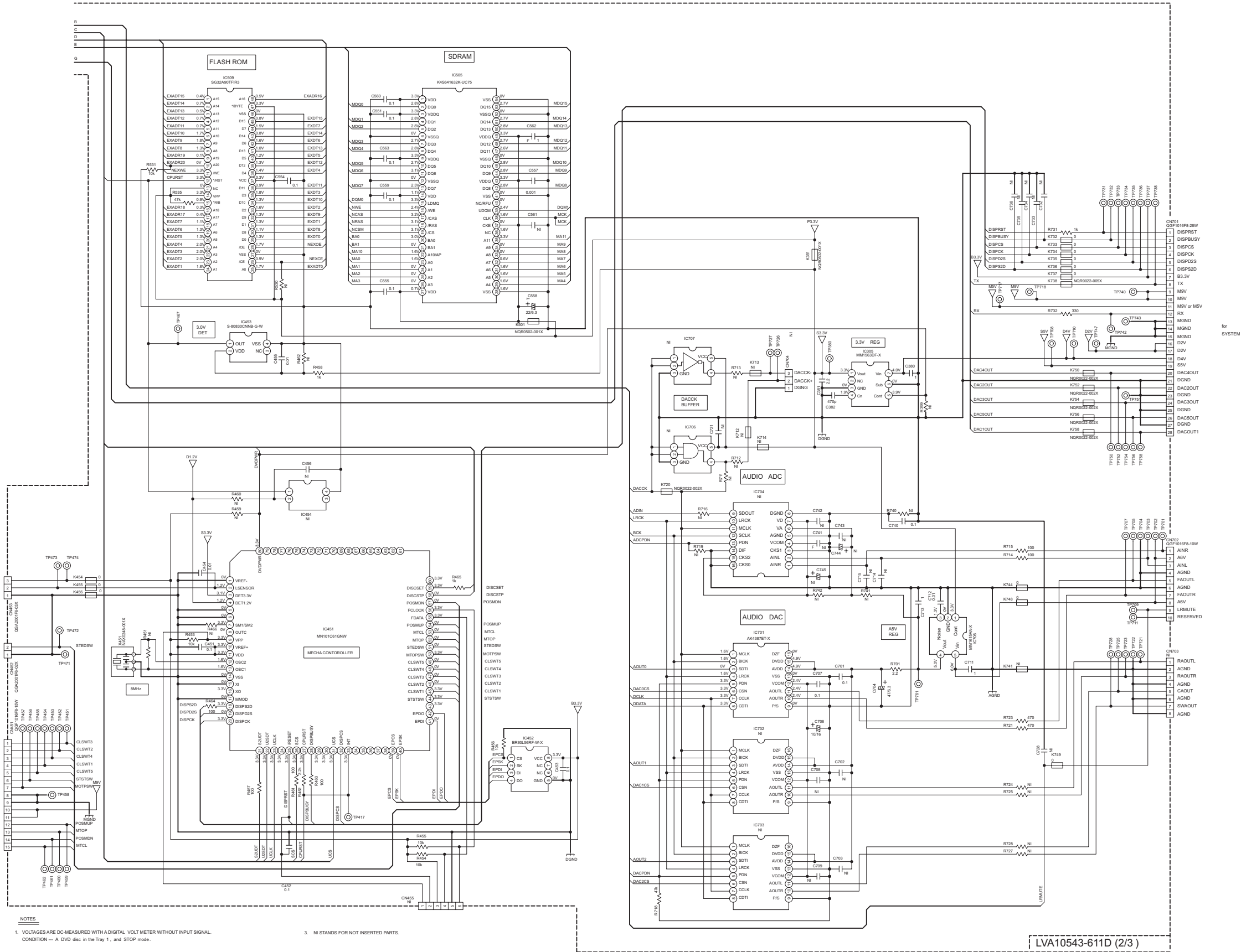
PICKUP ASS'Y
QAL0786-*** (OPR-652PH*)
TRA MECHA ASS'Y FXL-D20-1M
FEED MOTOR QAR0165-001
SPINDLE MOTOR QAR0334-002



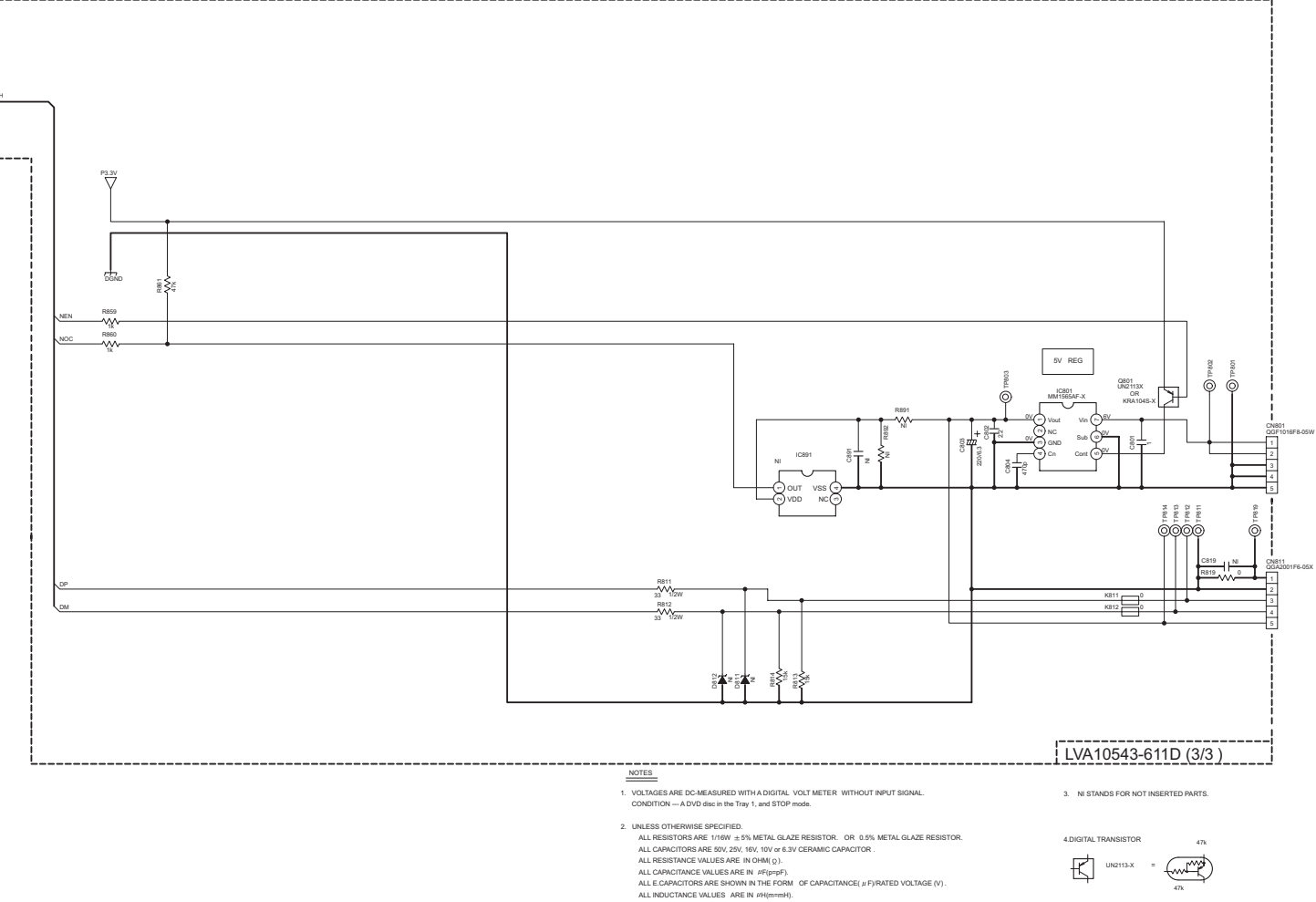
■ Front end section 2 (DX-J21,DX-J11)

LOADER ASS'Y
CH5-BASE-1

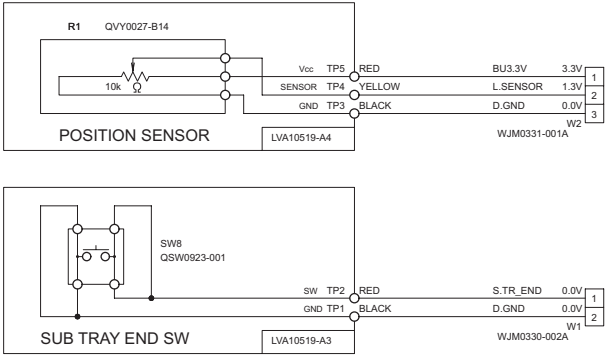
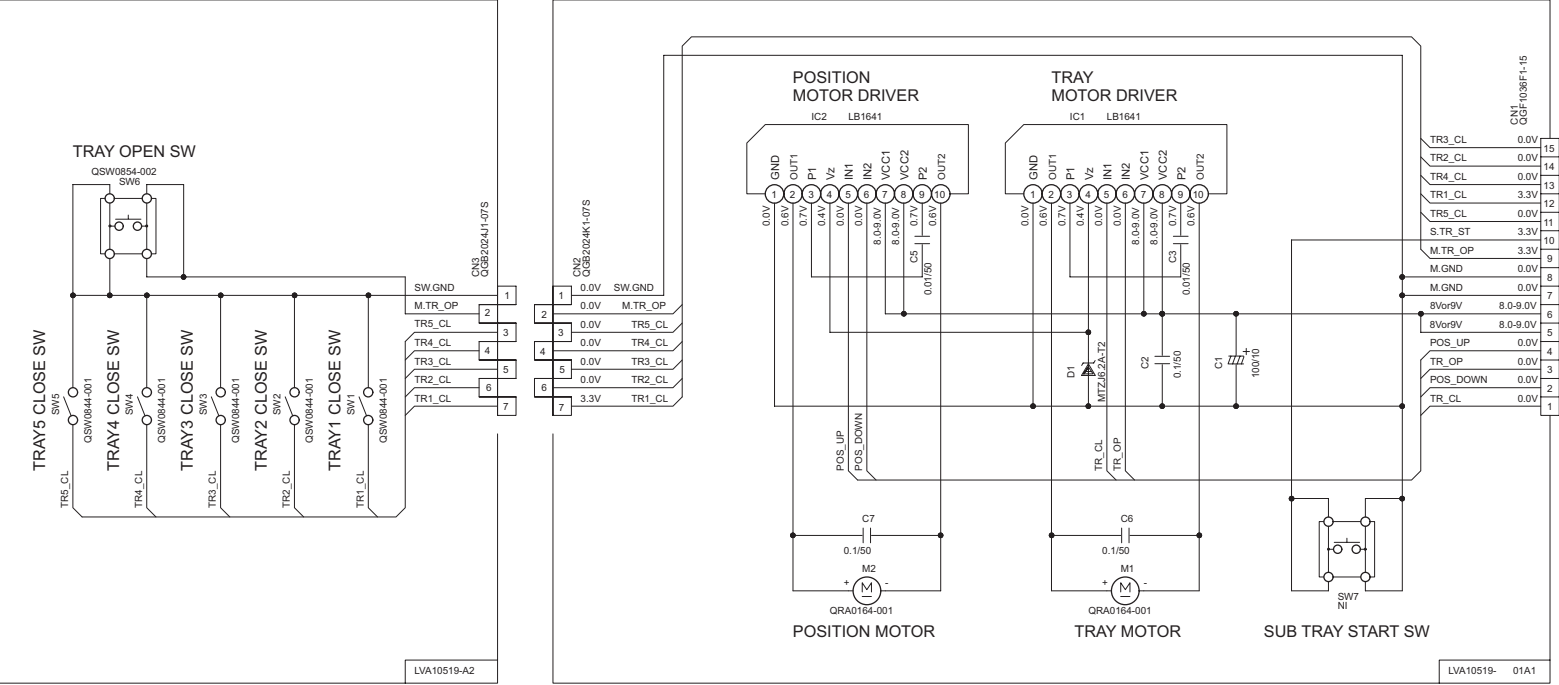
See
LVS20135-002A



■ Front end section 3 (DX-J21,DX-J11)



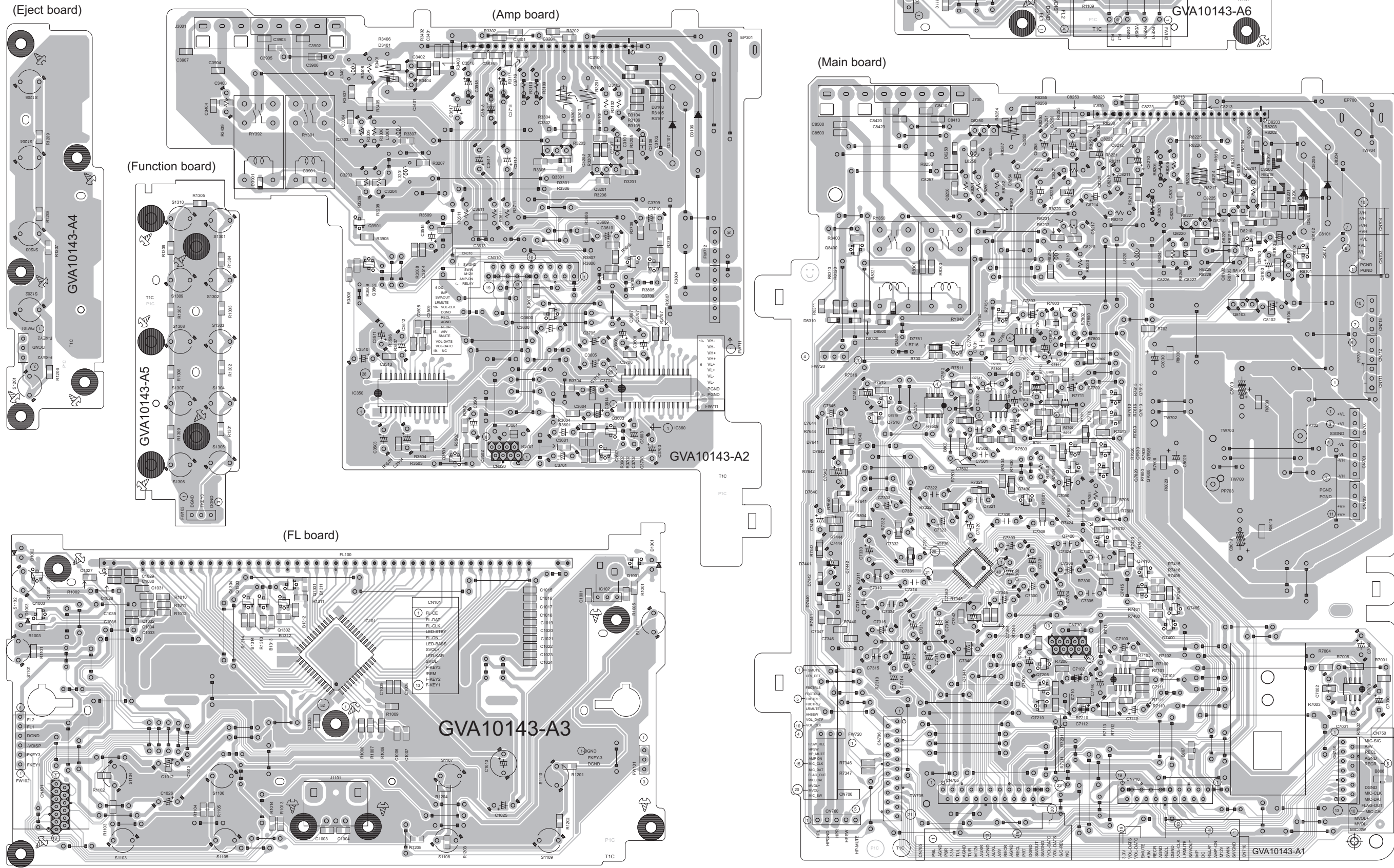
■ Loader section (DX-J21,DX-J11)



- NOTES
- VOLTAGES ARE DC-MEASURED WITH A DIGITAL VOLT METER.
CONDITION: DISC1 STOP
 - UNLESS OTHERWISE SPECIFIED.
ALL CAPACITORS ARE SHOWN IN THE FORM OF CAPACITANCE(μF)/RATED VOLTAGE(V).
 - NI STANDS FOR NOT INSERTED PARTS.

Printed circuit board

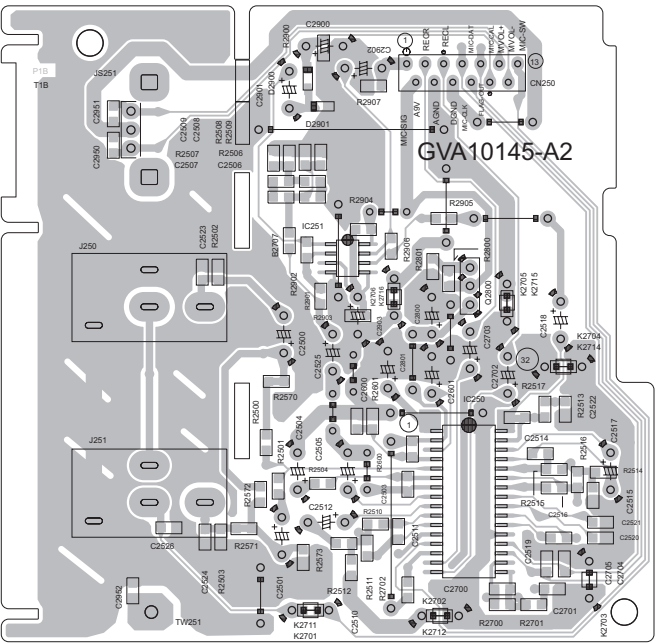
- Main board
- Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)
- Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



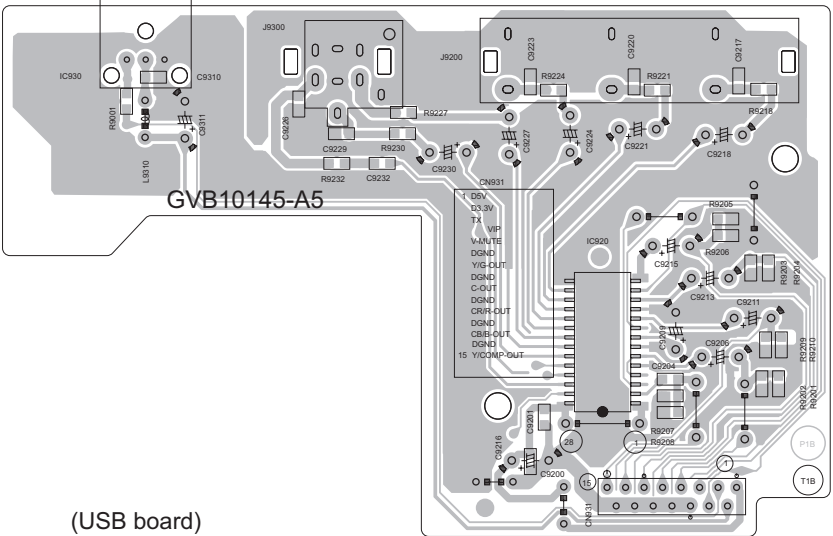
■ Micom board Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)
Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)

(Micom board)

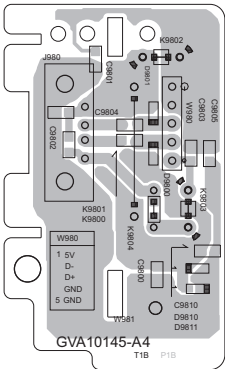
(Mic board)



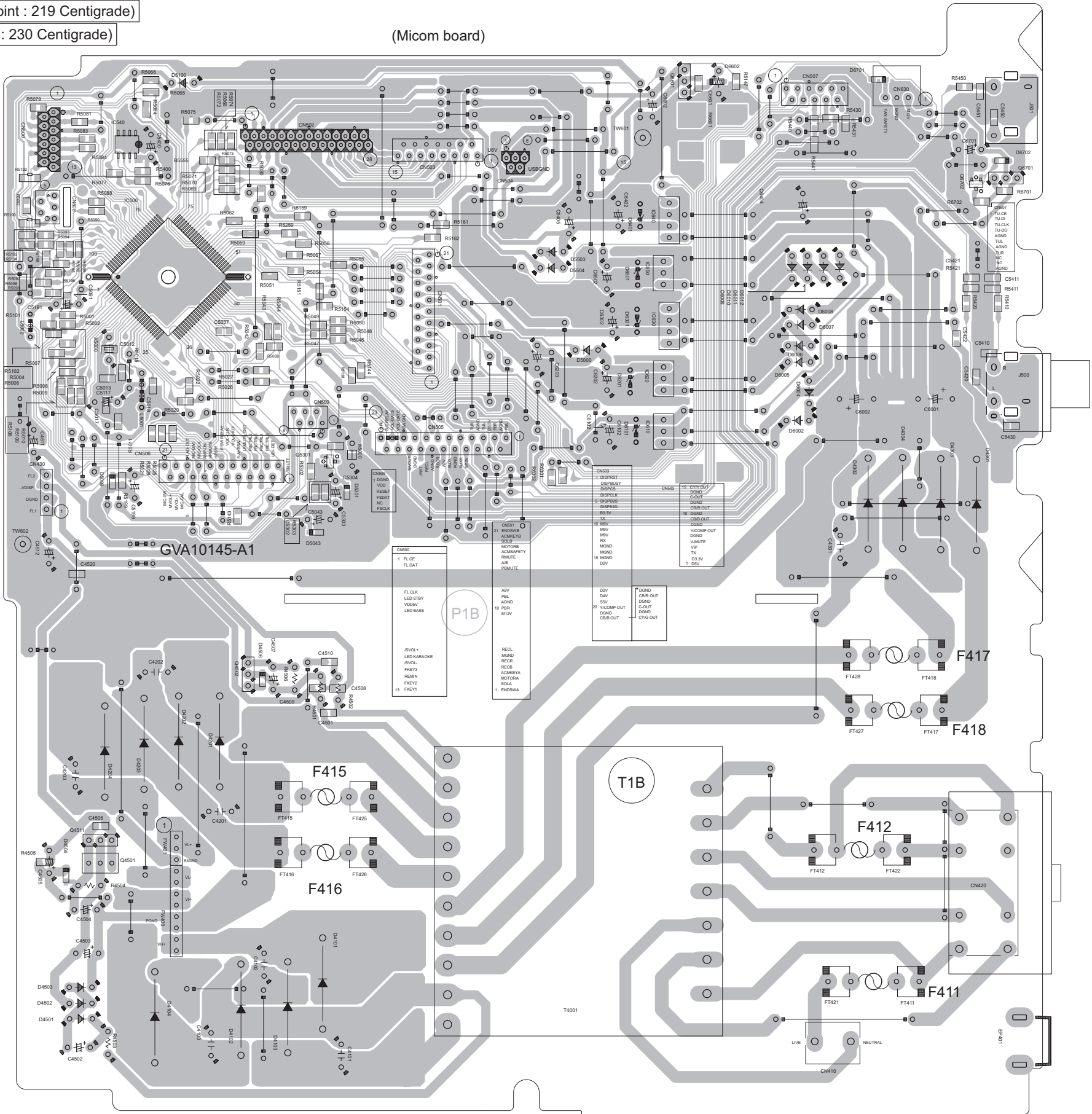
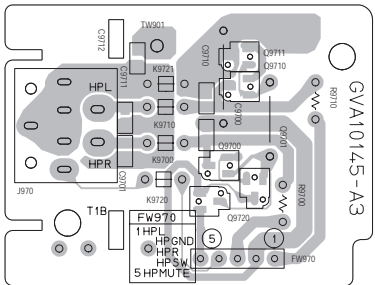
(Video board)



(USB board)



(Headphone board)

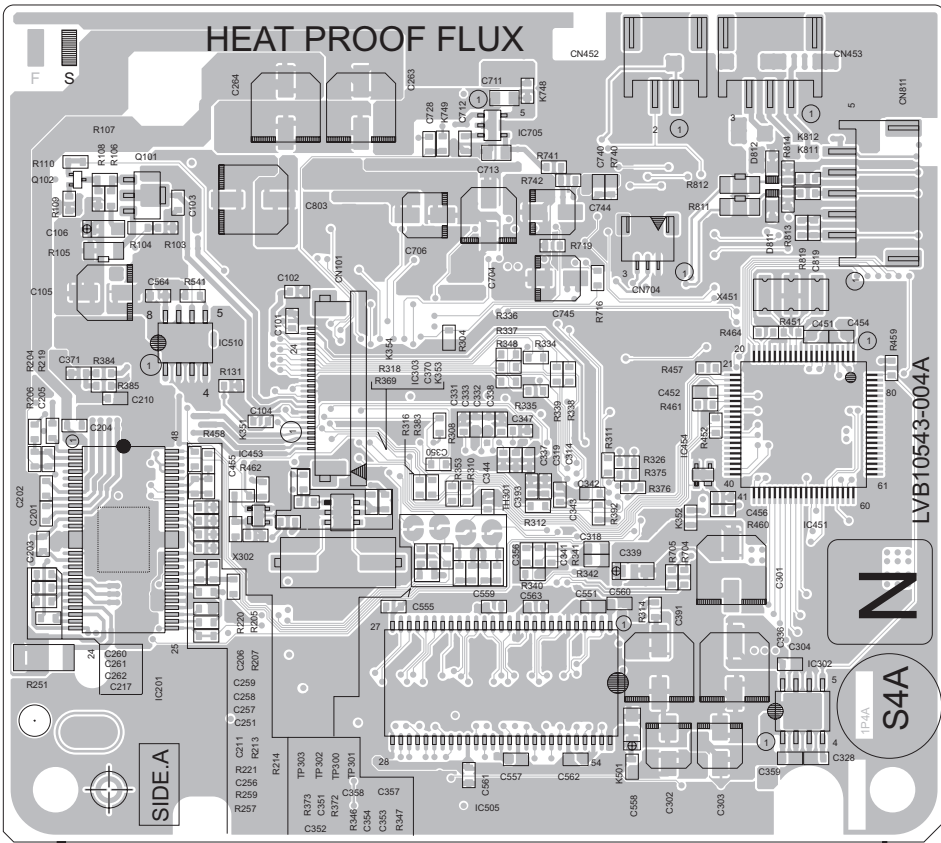


■ Front end board

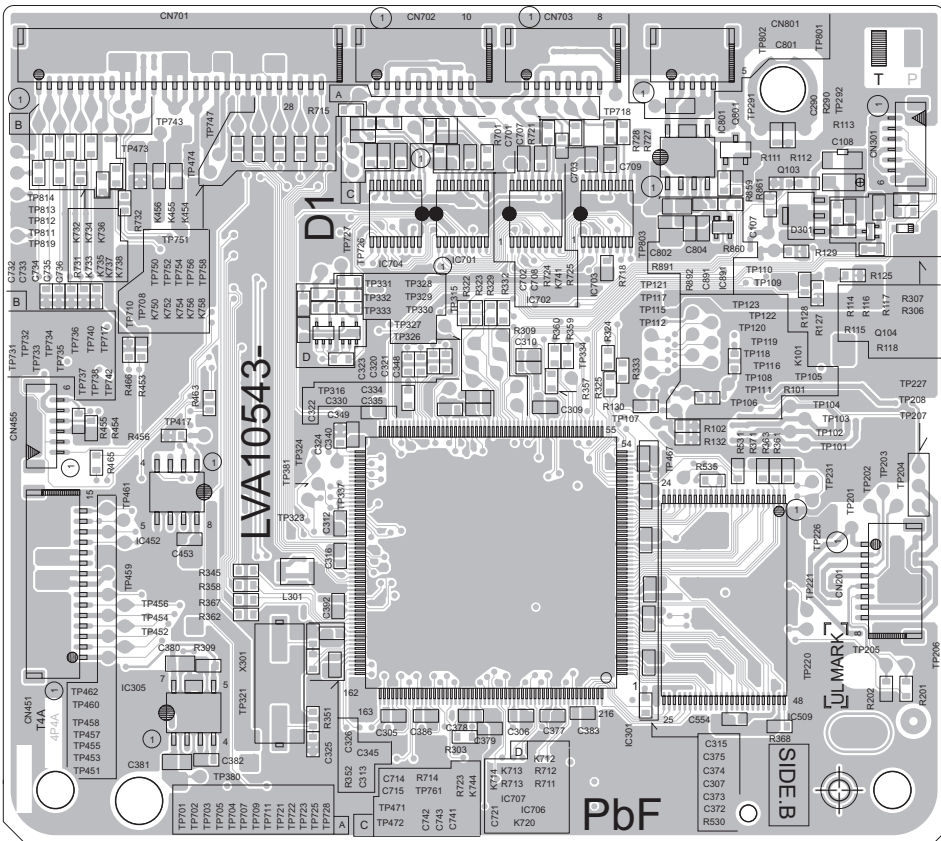
Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

forward side

Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



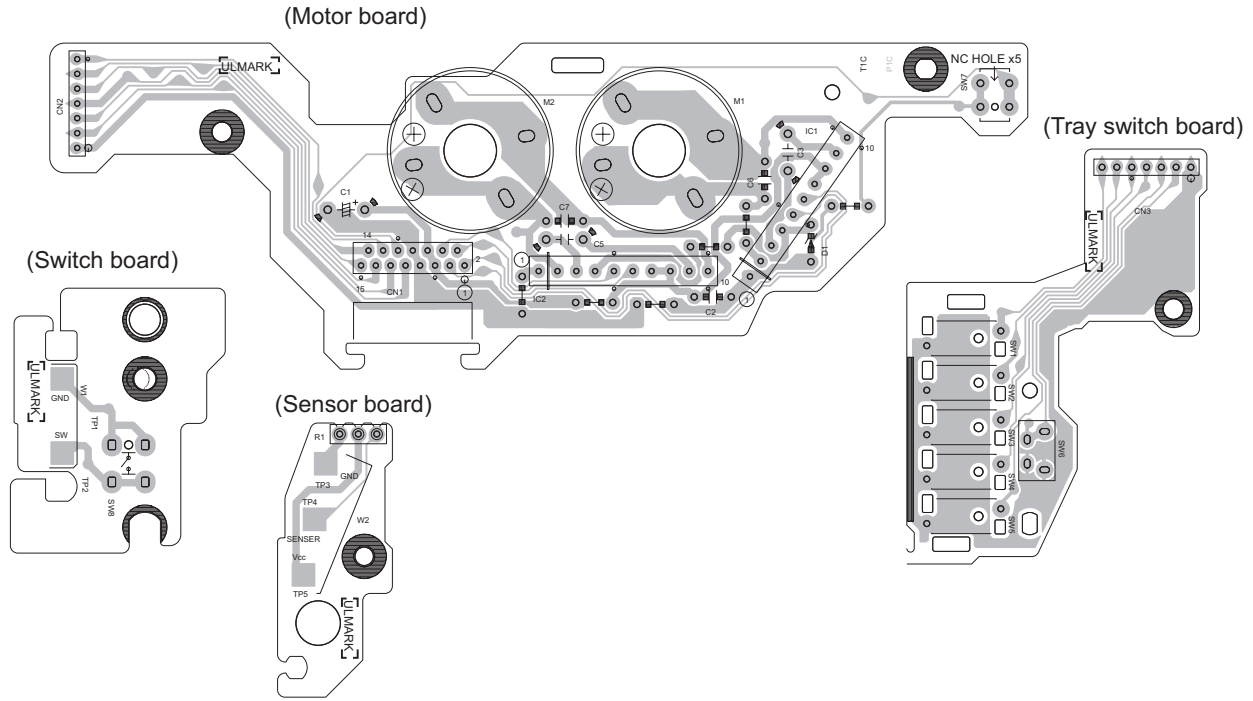
reverse side



■ Loader board

Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



■ Cassette board

Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



< MEMO >



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